Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of the Claims:

1. (Currently Amended) A device enclosure comprising:

a chassis including a top wall and an opposing bottom wall; and

a thermo-siphon device formed as an integral part of the top wall of the chassis, the thermo-siphon device including ~~first heat pipe and a second heat pipe,~~ a vaporizing end ~~of the first and second heat pipe~~ coupled to a first metal plate, and a condensing end ~~of the first heat pipe~~ coupled to a second metal plate, the top wall partially encloses the thermo-siphon device~~, and a condensing end of the second heat pipe coupled to a third metal plate~~.

2. (Currently Amended) The device enclosure of claim 1, wherein the device is an electronic device.

3. (Currently Amended) The device enclosure of claim 2, wherein the device enclosure is a computer chassis.

4. (Currently Amended) The device enclosure of claim 1, wherein the device is a non-electronic device.

5. (Cancelled).

6. (Cancelled).

7. (Cancelled).

8. (Cancelled).

9. (Currently Amended) The device enclosure of claim 1, wherein the top wall is fabricated from a metallic material.

10. (Currently Amended) The device enclosure of claim 1, wherein the thermo-siphon device is embedded in a cavity of the wall.

11. (Currently Amended) The device enclosure of claim 10, wherein the cavity is created during a fabrication process of the wall.

12. (Canceled) ~~The device of claim 1, wherein the wall partially encloses the thermo-siphon device.~~

13. (Currently Amended) The device enclosure of claim ~~12~~, wherein a portion of the thermo-siphon device is exposed to an interior of the enclosure.

14. (Currently Amended) The device enclosure of claim 12, wherein a portion of the thermo-siphon device is exposed to a heat sink.

15. (Cancelled).

16. (Cancelled).

17. (Currently Amended) The device enclosure of claim 1, wherein the thermo-siphon device is secured to a wall cavity through the means selected from the group consisting of a support provided by cavity walls, a thermal epoxy, and an interference fit with the wall cavity.

18. (Cancelled).

19. (Currently Amended) A system comprising:

a chassis including a top wall and an opposing wall; and

a thermo-siphon device formed as an integral part of the top wall of the chassis, the thermo-siphon device including ~~first heat pipe and a second heat pipe,~~ a

vaporizing end ~~of the first and second heat pipe~~ coupled to a first metal plate, and a condensing end ~~of the first heat pipe~~ coupled to a second metal ~~plate, and a condensing end of the second heat pipe coupled to a third metal~~ plate, the top wall partially encloses the thermo-siphon device. ~~:~~

20. (Cancelled).

21. (Cancelled).

22. (Original) The system of claim 19, wherein the chassis is a computer chassis.

24. (Currently Presented) A computer chassis comprising:

a chassis including a top wall and an opposing wall; and

a thermo-siphon device formed as an integral part of wall of the chassis, the thermo-siphon device including ~~first heat pipe and a second heat pipe,~~ a vaporizing end ~~of the first and second heat pipe~~ coupled to a first metal plate, and a condensing end ~~of the first heat pipe~~ coupled to a second metal plate, the top wall partially encloses the thermo-siphon device ~~and a condensing end of the second heat pipe coupled to a third metal plate~~.

25. (Original) The computer chassis of claim 24, wherein the thermo-siphon device is a heat pipe.

26. (Original) The computer chassis of claim 24, wherein the computer chassis is a notebook computer base.

27. (Cancelled).

28. (Canceled) ~~The computer chassis of claim 24, wherein the thermo-siphon device is embedded in the wall during the manufacturing process of the skin.~~